



# Qualcomm Centriq 2400 Processor

Qualcomm Datacenter Technologies, Inc has developed the world's first 10nm server processor, tailored to the emerging demands of highly-scalable, performant, power-efficient servers that will fuel the next wave of cloud datacenters. This single-chip, platform-level solution delivers a balanced combination of compute, memory and high speed I/O for high performance per thread at a superior performance per Watt. Our custom, highly scalable 48-core design features the Qualcomm Falkor CPU, an Armv8 CPU core that's optimized for cloud-computing workloads. The Qualcomm Centriq 2400 is Arm SBSA Level 3 Compliant - simplifying development efforts for our ecosystem partners.

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## Specifications

<b>CPU</b>	<b>CPU Cache:</b> 64KB L1 instruction cache with 24KB single-cycle L0 cache, 32KB L1 data cache, Dual-core structure with 512KB shared unified L2 cache with ECC, Up to 60MB distributed unified L3 cache with ECC, Integrated L2 snoop filter, Cache QoS
<b>Process</b>	<b>Process Technology:</b> 10nm FinFET
<b>Memory</b>	<b>Memory Bandwidth:</b> 6 DDR4 memory channels, Up to 2667 MT/s per channel, 128 GB/s peak aggregate bandwidth, Inline bandwidth compression <b>Memory Capacity:</b> 6 x 128 GB/Channel - 768 GB capacity <b>Memory Type:</b> 64-bit DDR4 channels with 8-bit ECC, RDIMM and LRDIMM, Up to quad rank 3DS
<b>Interface</b>	<b>Supported Interfaces:</b> 32 lanes PCI Express Gen 3 up to 16 lanes SATA Gen 3, 2 PCIe Gen 3, 2 SATA, 2 SATA

**Qualcomm  
High-Speed  
Coherent  
Interconnect**

**Features:** Qualcomm proprietary protocol, Full cache and IO coherency, Bi-directional segmented coherent ring, Up to 268 GBps per ring segment, Shortest path routing

**SOC**

**Features:** Distributed architecture, Single chip platform-level solution, Arm SBSA Level 3 compliant, Integrated management controller

**Package**

**Package Type:** LGA (socketed)

**Package Size:** 55x55 mm

**Pins:** 2808 pins

**Pitch:** 1.0 mm Pitch